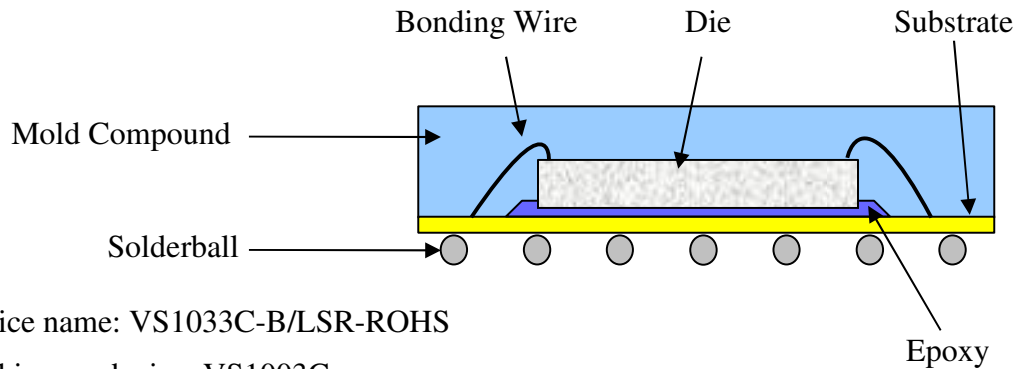


# Cross-Section View VS1033C 49pin FBGA (RoHS) Package



Device name: VS1033C-B/LSR-ROHS

Marking on device: VS1003C

## Substrate

plate composition: Cu, Au and Ni

plate thickness : Cu = 22.5 +/- 7.5 microns

Au = 0.5 to 1.2 microns

Ni = 5.0 microns minimum

**Total substrate thickness : 0.3MM +/- 0.04 MM**

## Material

Solderball	Sn 96.5%, Ag 3%, Cu 0.5% (Mitsui)
Substrate	HL832NX (Mitsubishi), AUS 308 (Taiyo)
Epoxy Die Attach	ABLEBOND 2000B (Ablestik)
Bonding Wire	25 um (MEM)
Mold Compound	EMEG760V (Sumitomo)